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1129 U.S. PTO
12/04/01PATENT APPLICATION
Attorney's Do. No. 9903-28

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

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10/006180
12/04/01

Box Patent Application
U. S. Patent and Trademark Office
P. O. Box 2327
Arlington, VA 22202

Enclosed for filing is a patent application under 37 CFR 1.53(b) of:

Inventor Tae-Sub CHANG, Dong-Ho LEE and Min-Young SON:
For: WAFER LEVEL PACKAGE INCLUDING GROUND METAL LAYER

Applicant requests FIG. 4A to be published with the application.

Enclosures:

- ☒ Specification (pages 1-7); claims (pages 8-10); abstract (page 11)
☒ SIX sheet(s) of FORMAL drawings
☒ Declaration or Combined Declaration and Power of Attorney
☒ Newly executed (original or copy)
☒ Assignment with cover sheet
 Assignee Name and Address: Samsung Electronics Co., Ltd.
 Suwon-city, Kyungki-do, Korea
☒ Certified copy of priority document
☒ Return Postcard

CLAIMS AS FILED				
For	Number Filed	Number Extra	Rate	Basic Fee \$740
Total Claims	20-20	0	x \$ 18 =	0
Independent Claims	2-3	0	x \$ 84 =	0
TOTAL FILING FEE				\$740

- ☒ PTO Form 2038 authorizing credit card payment for the above-listed fees is enclosed.



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Respectfully submitted,

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